



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50N06S4-09		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000667628							
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		370.39 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.120	0.57	0.57	5724	5724	
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		633		
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190		
	non noble metal	copper	7440-50-8	234.187	63.24	63.32	632267	633090	
wire	non noble metal	aluminium	7429-90-5	2.088	0.56	0.56	5637	5637	
encapsulation	organic material	carbon black	1333-86-4	1.257	0.34		3393		
	plastics	epoxy resin	-	21.996	5.94		59385		
	inorganic material	silicondioxide	60676-86-0	102.436	27.66	33.94	276562	339340	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10098	10098	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246	
solder	noble metal	silver	7440-22-4	0.054	0.01		147		
	non noble metal	tin	7440-31-5	0.043	0.01		117		
	non noble metal	lead	7439-92-1	2.074	0.56	0.58	5601	5865	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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